



SRA #312 No-Clean Flux, Solvent Based (2% Solids)

Key Features

- Excellent surface wetting
- Eliminates the need for cleaning soldered boards
- May be conformal coated without post-solder cleaning
- Can be used with lead free solder
- Conforms to ANSI-J-STD-004, Type ORL0

DESCRIPTION

SRA #312 No-Clean Flux, Solvent Based (2% Solids) flux is a specially formulated low-solids flux free of any halides, resin, or rosin. This flux was designed for soldering high quality electronic printed circuit boards (PCBs), such as, through-hole, mixed technology, and surface mount assemblies while eliminating the need for a post cleaning operation. **SRA #312 No-Clean Flux, Solvent Based (2% Solids)** is formulated for foam or spray applications as supplied.

APPLICATION

WAVE SOLDERING:

SRA #312 No-Clean Flux, Solvent Based (2% Solids), No-Clean Flux may be applied by foam, spray, or wave application. The optimum topside PCB preheat temperature recommendation is 93-115°C/200-240°F. Too low a preheat setting is indicated by post-solder residues on PCBs that look like water stains. A solder-bath temperature of 480°F ± 20°F is recommended for optimum result.

For optimum soldering results, use the following guidelines:

- ❶ Make certain that the PCB surfaces are free of any oil, grease, or other impurities.
- ❷ Maintain a consistent foam head by narrowing the flux chimney, or using dual flux stones.
- ❸ Add fresh flux to maintain proper flux level in flux tank.
- ❹ Replace the flux daily unless a sealed, self-contained system is used; such as in a spray fluxing system.
- ❺ Regularly clean the fluxing equipment. Never leave foaming stone in flux when pressure is not applied.
- ❻ Clean fluxing stone in flux thinner.
- ❼ When foam fluxing, flux properties can be maintained by monitoring the specific gravity. However, control by checking the acid value is recommended as the most accurate measure. Titration kits are available from Superior Flux.
- ❽ Add flux thinner when needed.

SRA #312 No-Clean Flux, Solvent Based (2% Solids) is also formulated for use in manual soldering applications for electronic assemblies. A soldering iron temperature between 315-400°C / 600-750°F is recommended for optimum results. Apply flux to area that is being soldered. Post-soldering residues are water-soluble and can be removed with DI, distilled, or RO water.

SAFETY PRECAUTIONS

SRA #312 No-Clean Flux, Solvent Based (2% Solids) flux is a flammable product and should be handled with care and the normal precautions taken when working with chemical products.

When soldering with **SRA #312 No-Clean Flux, Solvent Based (2% Solids)** adequate exhaust ventilation should be provided. Avoid contact with eyes, skin, and mucous membranes. Always wear NIOSH approved safety equipment when working with chemicals. Store in plastic containers away from heat.

Refer to Material Safety Data Sheet (MSDS) for additional safety information.

Store flux in an area with controlled temperature between 18-25°C/64-77°F.



